TAIYO YUDEN Launches Bluetooth® 5 Compatible Module with Embedded Software Capable of wireless communications with simple commands, contributing to a reduction in development period

TOKYO, December 18, 2018—TAIYO YUDEN CO., LTD. announced today the launch of a new Bluetooth® 5 compatible wireless communications module with its proprietary embedded software, EYSKBNUWB-WX (10.0×15.4×2.0 mm). This product is ideal for IoT-related devices, including sensor networks containing various sensors used in combination, healthcare equipment, and home automation equipment.

The product, which consists of our existing product, EYSKBNZWB (10.0×15.4×2.0 mm), and our proprietary embedded software, allows you to realize wireless communications simply by inputting simple commands from the outside, thereby contributing to a reduction in the development period for implementing wireless communications functions to your devices.

TAIYO YUDEN TECHNO SOLUTIONS CO., LTD. (Takasaki City, Gunma Prefecture, Japan) will commence mass production of the product in January 2019, with a sample price of 3,000 yen per unit.

Technology Background
IoT-related devices are required to be operable in sensor networks everywhere and to have an extremely low power consumption. Software for wireless communications must be created when developing such devices, which involves various problems, including the development period.

In response to this situation, TAIYO YUDEN commercialized EYSKBNUWB-WX, which consists of a Bluetooth® 5 compatible wireless communications module, EYSKBNZWB, and its proprietary embedded software. Bluetooth® 5 is the latest version of Bluetooth®, widely used as a low power consumption wireless communications standard. This product allows you to realize wireless communications simply by inputting simple commands from the outside, thereby contributing to reducing the development period.

TAIYO YUDEN will continue to meet market needs and enhance its product lineup by developing smaller and more reliable products.

The product will be exhibited at the TAIYO YUDEN booth in CES 2019, which will take place from January 8, 2019 in Las Vegas, Nevada, the United States of America.
*1 The Bluetooth® word mark and logos are owned by Bluetooth SIG, Inc. and the use of such marks by TAIYO YUDEN CO., LTD. is under license.
*2 The sample price mentioned in this release is our direct sales price. When considering purchasing via a sales agency, please contact the agency for the sample price.

Applications
Wireless communications modules for IoT-related devices, including sensor networks in which various sensors are used in combination, healthcare equipment, and home automation equipment

Characteristics

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Size (L×W×H)</th>
<th>Specification</th>
<th>I/F</th>
<th>Certification</th>
<th>Temperature</th>
</tr>
</thead>
<tbody>
<tr>
<td>EYSKBNUWB-WX</td>
<td>10.0×15.4×2.0mm</td>
<td>V5.0 BLE Single Central/Peripheral 2Mbps/Long range</td>
<td>UART SPI USB GPIO</td>
<td>Japan U.S.A. Canada CE*</td>
<td>-40 to +85°C</td>
</tr>
</tbody>
</table>

* The ETSI EN 300 328 v2.1.1 test report can be provided.